

SW069R06VT-VB Datasheet N-Channel 60 V (D-S) MOSFET

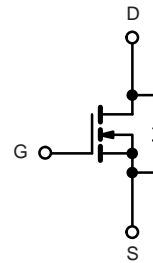
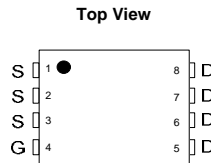
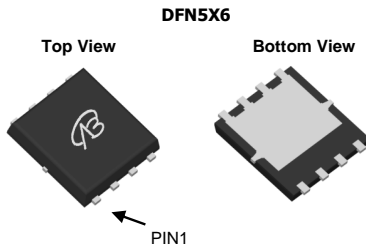
| PRODUCT SUMMARY | | |
|-----------------|---------------------------|------------------------|
| V_{DS} (V) | $R_{DS(on)}$ (Ω) | I_D (A) ^a |
| 60 | 0.006 at $V_{GS} = 10$ V | 80 |
| | 0.007 at $V_{GS} = 4.5$ V | 65 |

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:



RoHS
COMPLIANT



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted) | | | | |
|---|----------------|----------------|--------------------------------------|------|
| Parameter | | Symbol | Limit | Unit |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current ($T_J = 175$ °C) ^b | $T_C = 25$ °C | I_D | 80 | A |
| | $T_C = 100$ °C | | 65 ^a | |
| Pulsed Drain Current | | I_{DM} | 100 | |
| Continuous Source Current (Diode Conduction) | | I_S | 70 ^a | |
| Avalanche Current | | I_{AS} | 90 | |
| Single Avalanche Energy (Duty Cycle ≤ 1 %) | $L = 0.1$ mH | E_{AS} | 405 | mJ |
| Maximum Power Dissipation | $T_C = 25$ °C | P_D | 136 | W |
| | $T_A = 25$ °C | | 3 ^b , 8.3 ^{b, c} | |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | - 55 to 175 | °C |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|-----------------|------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maximum Junction-to-Ambient ^a | $t \leq 10$ sec | R_{thJA} | 15 | 18 | °C/W |
| | Steady State | | 40 | 50 | |
| Maximum Junction-to-Case | | R_{thJC} | 0.85 | 1.1 | |

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. $t \leq 10$ s.

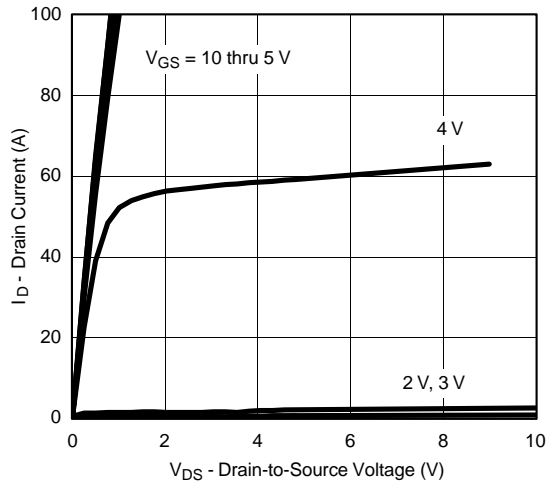
| SPECIFICATIONS (T _J = 25 °C, unless otherwise noted) | | | | | | |
|---|---------------------|--|------|-------------------|-------|------|
| Parameter | Symbol | Test Conditions | Min. | Typ. ^a | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | 60 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 2.5 | | 4 | |
| Gate-Body Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 20 V | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 60 V, V _{GS} = 0 V | | | 1 | μA |
| | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C | | | 50 | |
| | | V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C | | | 250 | |
| On-State Drain Current ^b | I _{D(on)} | V _{DS} = 5 V, V _{GS} = 10 V | 60 | | | A |
| Drain-Source On-State Resistance ^b | R _{DS(on)} | V _{GS} = 10 V, I _D = 20 A | | 0.006 | | Ω |
| | | V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C | | 0.010 | | |
| | | V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C | | 0.015 | | |
| | | V _{GS} = 4.5 V, I _D = 15 A | | 0.007 | | |
| Forward Transconductance ^b | g _{fs} | V _{DS} = 15 V, I _D = 20 A | | 60 | | S |
| Dynamic | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 2650 | | pF |
| Output Capacitance | C _{oss} | | | 470 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 225 | | |
| Total Gate Charge ^c | Q _g | V _{DS} = 30 V, V _{GS} = 10 V, I _D = 50 A | | 47 | 70 | nC |
| Gate-Source Charge ^c | Q _{gs} | | | 10 | | |
| Gate-Drain Charge ^c | Q _{gd} | | | 12 | | |
| Turn-On Delay Time ^c | t _{d(on)} | V _{DD} = 30 V, R _L = 0.6 Ω I _D ≅ 50 A, V _{GEN} = 10 V, R _g = 2.5 Ω | | 10 | 20 | ns |
| Rise Time ^c | t _r | | | 15 | 25 | |
| Turn-Off Delay Time ^c | t _{d(off)} | | | 35 | 50 | |
| Fall Time ^c | t _f | | | 20 | 30 | |
| Source-Drain Diode Ratings and Characteristics (T_C = 25 °C) | | | | | | |
| Pulsed Current | I _{SM} | | | | 60 | A |
| Diode Forward Voltage | V _{SD} | I _F = 20 A, V _{GS} = 0 V | | 1 | 1.5 | V |
| Reverse Recovery Time | t _{rr} | I _F = 20 A, di/dt = 100 A/μs | | 45 | 100 | ns |

Notes:

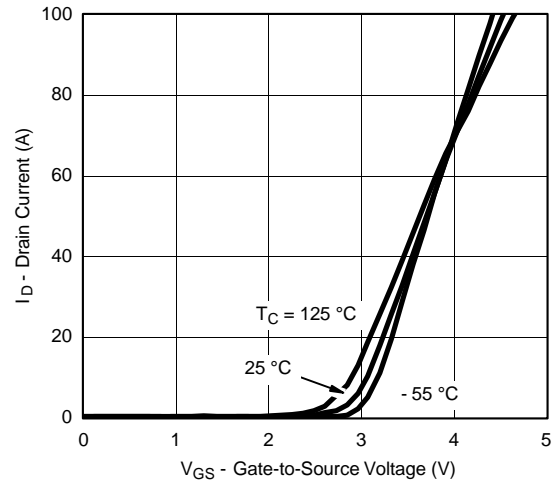
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

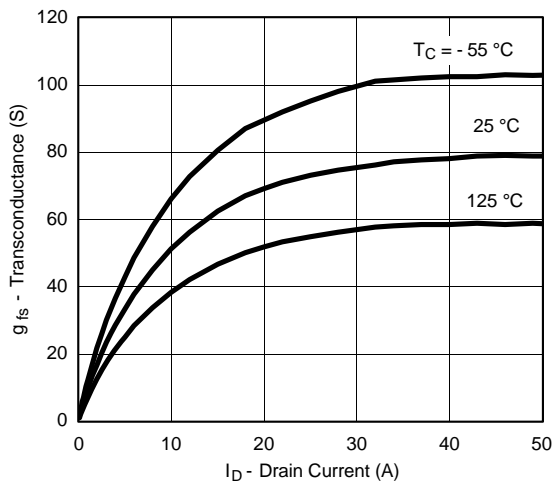
TYPICAL CHARACTERISTICS (25 °C unless noted)



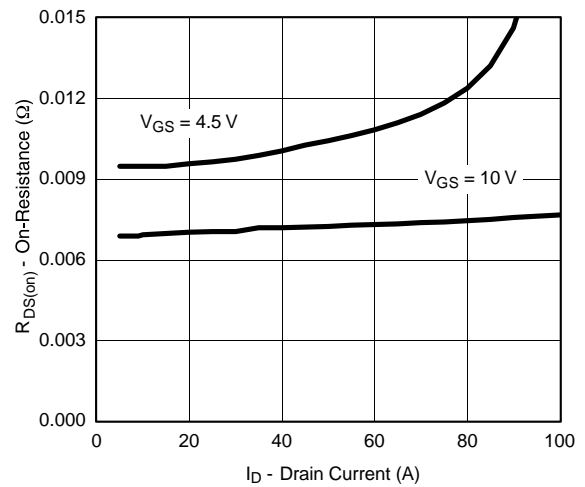
Output Characteristics



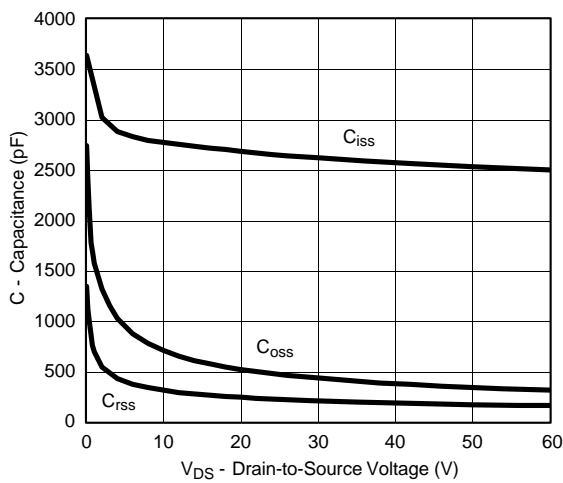
Transfer Characteristics



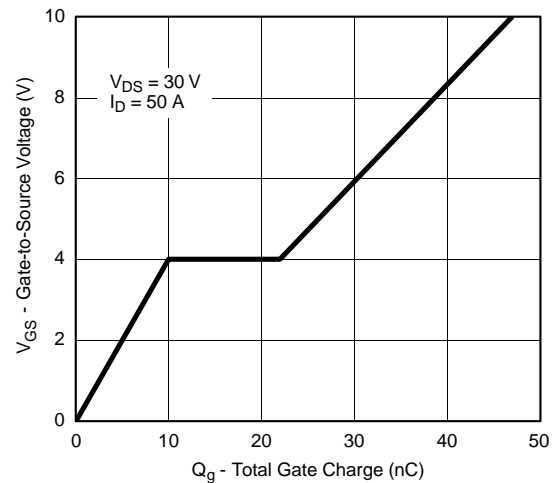
Transconductance



On-Resistance vs. Drain Current

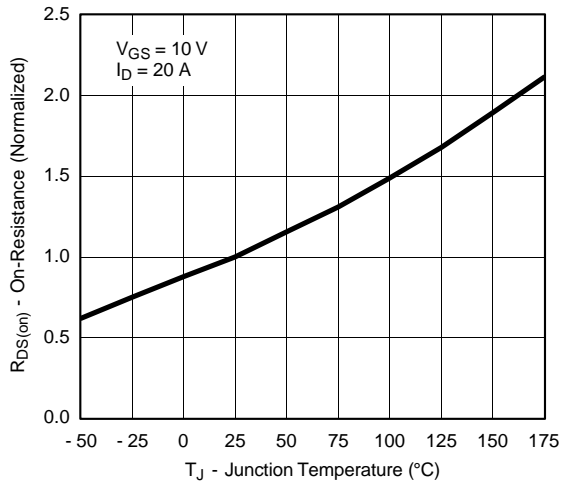


Capacitance

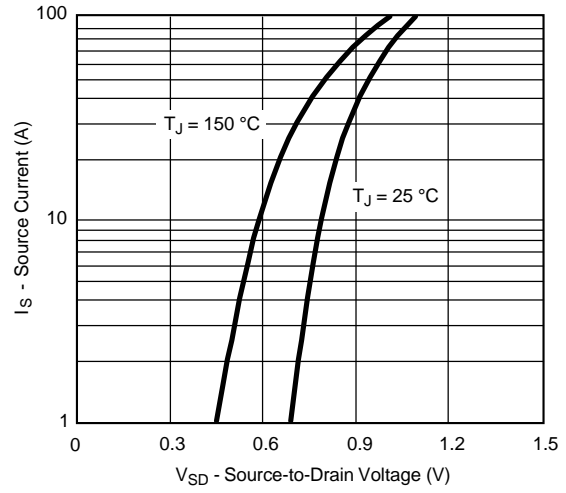


Gate Charge

TYPICAL CHARACTERISTICS (25 °C unless noted)

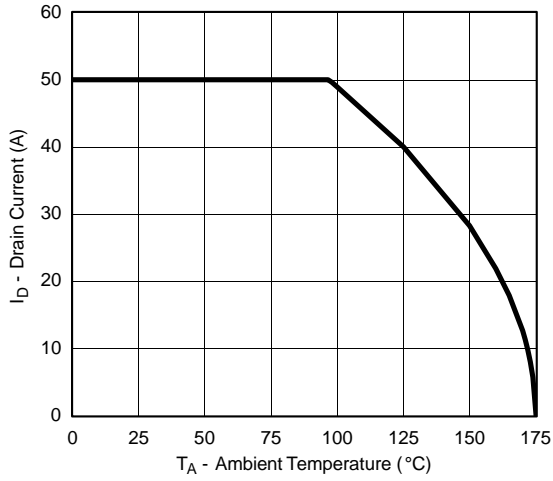


On-Resistance vs. Junction Temperature

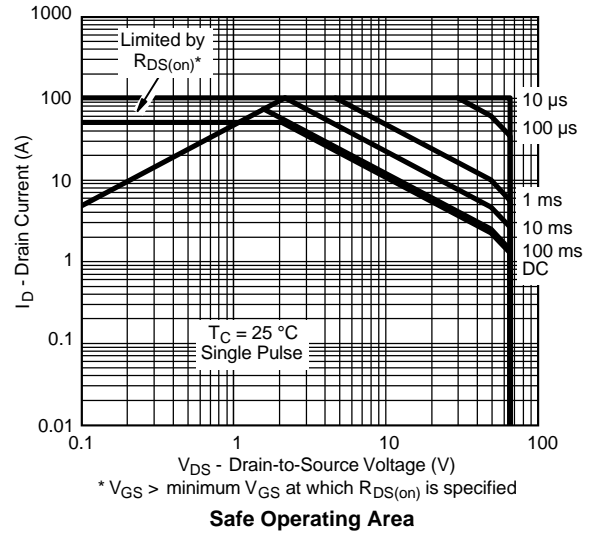


Source-Drain Diode Forward Voltage

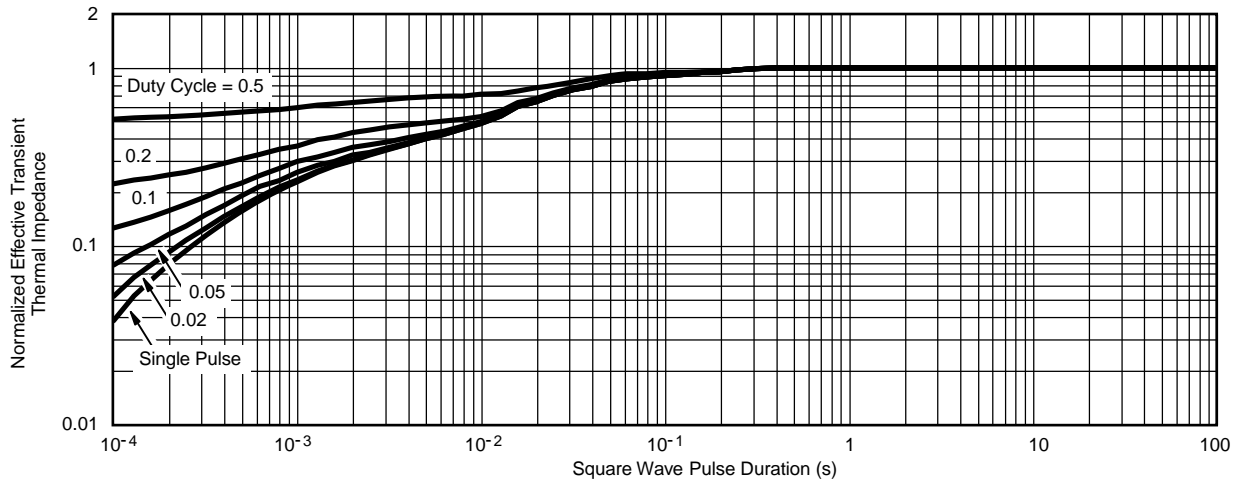
THERMAL RATINGS



Maximum Drain Current vs. Ambient Temperature

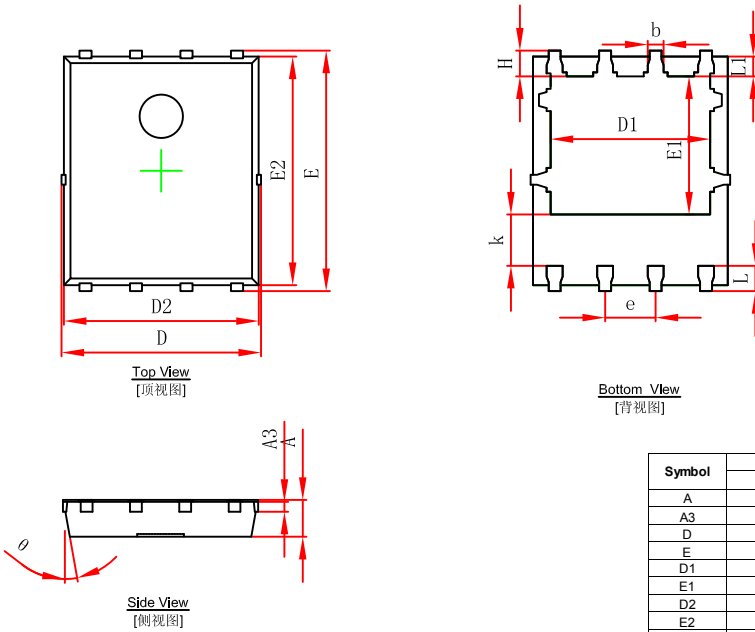


Safe Operating Area



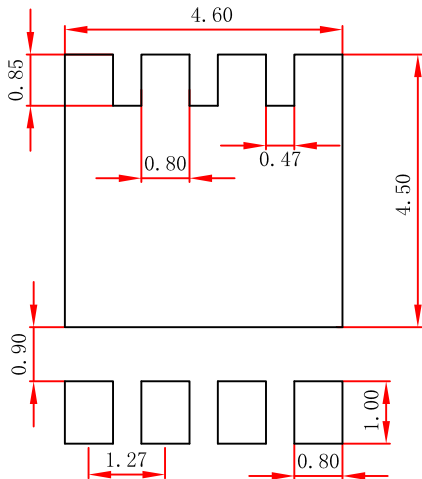
Normalized Thermal Transient Impedance, Junction-to-Case

PDFNWB5x6-8L Package Outline Dimensions



| Symbol | Dimensions in Millimeters | | Dimensions in Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A3 | 0.254REF. | | 0.010REF. | |
| D | 4.944 | 5.096 | 0.195 | 0.201 |
| E | 5.974 | 6.126 | 0.235 | 0.241 |
| D1 | 3.910 | 4.110 | 0.154 | 0.162 |
| E1 | 3.375 | 3.575 | 0.133 | 0.141 |
| D2 | 4.824 | 4.976 | 0.190 | 0.196 |
| E2 | 5.674 | 5.826 | 0.223 | 0.229 |
| k | 1.190 | 1.390 | 0.047 | 0.055 |
| b | 0.350 | 0.450 | 0.014 | 0.018 |
| e | 1.270TYP. | | 0.050TYP. | |
| L | 0.559 | 0.711 | 0.022 | 0.028 |
| L1 | 0.424 | 0.576 | 0.017 | 0.023 |
| H | 0.574 | 0.726 | 0.023 | 0.029 |
| θ | 10° | 12° | 10° | 12° |

PDFNWB5x6-8L Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05 mm.
 3. The pad layout is for reference purposes only.

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